

Electronic Patent Application Fee Transmittal

Application Number:	10789637			
Filing Date:	27-Feb-2004			
Title of Invention:	Flip chip semiconductor die internal signal access system and method			
First Named Inventor/Applicant Name:	Brian S. Schieck			
Filer:	John F. Ryan			
Attorney Docket Number:	NVID-P001125			
Filed as Large Entity				
Utility under 35 USC 111(a) Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 1 month with \$0 paid	1251	1	130	130

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	810	810
Total in USD (\$)				940